

Features & Benefits

- Value Thermal Conductivity and Resistance
- Two-part (2:1 mix ratio) Heat Cure
- Low flow in elevated temperature
- High temperature applications
- Proven Long term reliability
- RoHS compliant, Halogen free and lead-free process
- Non-silicone based with zero outgassing

Thermal Conductive Ink is an epoxy resin base (two-part) with 2:1 mixing ratio thermal conductive and electrical isolating material ideal for dispensing application.

Applications

- High power density applications which required low thermal resistance
- Industrial Motor, servo motor and EV motor
- LED modules
- Power Supplies and Semiconductors packaging
- Household appliances and consumer electronics

Configurations and Storage Conditions

The TCI C family comes in 2 parts for a single product: TCI-C60B-2K (Part A and Part B)

- Refrigeration <10°C for 1 year from manufacturing date
- Room temp. 25±5°C, RH<70% for 3 months (unopened)
- Room temp. 25±5°C, RH<70% for 1 week (once opened)

We provide custom solutions for your applications. For further inquiries, please contact your local sales agent or directly to TCLAD sales in your region



Property	Method (Units)	TCI-C60B-2K-A (Typ.)	TCI-C60B-2K-B (Typ.)
Resin Base	Chemistry	Epoxy	Epoxy
Mixing Ratio	-	2	1
Color	Visual	Black	Yellow
Hardness	ASTM D2240 (Shore00)	99	99
Thermal Conductivity	TO220 (W/mK)	1.5	1.5
Thermal Conductivity	ASTM D5470 (W/mK)	0.4	0.4
Viscosity	ASTM D2196 (cP)	40000 ± 10%	40000 ± 10%
Specific Gravity	ASTM D792 (g/cm3)	2.62 ± 0.3	2.62 ± 0.3
Operating Temperature Range	- (°C)	-40°C to 150°C	-40°C to 150°C
Glass Transition Temperature (Tg)	IPC-TM-650 2.4.25 (°C)	>110	>110
Thermal Degradation Temperature	IPC-TM-650 2.4.24.6 (°C)	>300	>300
Curing Condition [°C/ min]	- [°C/ min]	90±5°C ≥90 min	90±5°C ≥90 min
Outgassing	ASTM E595 (%)	0	0
Shelf Life	Storage Temp < 10°C (months)	12	12
Package Options	Weight	2Kg	1Kg

